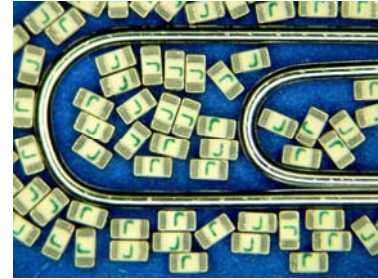


# SolidMatrix® 0603 High Inrush Current Surface Mount Fuses



## Features:

- High inrush current withstanding capability
- Ceramic Monolithic structure
- Silver fusing element and silver termination with nickel and tin plating
- RoHS compliant materials
- Standard EIA 0603/EIAJ1608 size
- Symmetrical design with marking on both sides (optional)
- Operating temperature: -55°C to +125°C (with de-rating)



## Clear-Time Characteristics:

% of Current Rating	Clear-time at 25°C	
100%	4 hours min.	
200%	1 second min.	60 seconds max.
1000%	0.0002 seconds min.	0.02 seconds max.

**Agency Approval:** Recognized Under the Components Program of Underwriters Laboratories. File Number: E232989

**Patents:** U.S. Patent numbers 6,034,589; 6,228,230; 6,602,766; 7,268,661 B2; and other pending patents.

## Interrupting Ratings:

50A at rated voltage

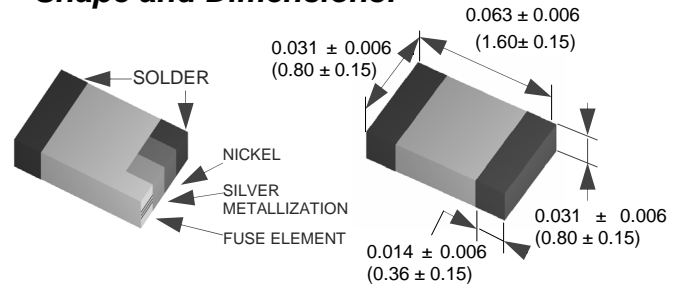
**Marking(Optional):** Green Marking Character Code  
1A:E, 1.5A:G, 2A:I, 2.5A:J, 3A:K, 3.5A:L, 4A:M, 4.5A:T, 5A:N

## Ordering Information:

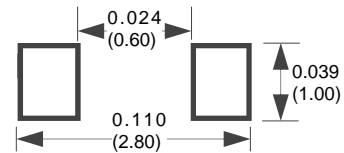
Part Number	Current Rating (A)	Voltage Rating (VDC)	Nominal Cold DCR ( $\Omega$ ) <sup>1</sup>	Nominal $I^2t$ ( $A^2s$ ) <sup>2</sup>
F0603HI1000V032T	1.0	32	0.190	0.08
F0603HI1500V032T	1.5	32	0.101	0.11
F0603HI2000V032T	2.0	32	0.057	0.24
F0603HI2500V032T	2.5	32	0.042	0.56
F0603HI3000V032T	3.0	32	0.030	0.72
F0603HI3500V032T	3.5	32	0.022	1.10
F0603HI4000V032T	4.0	32	0.018	2.08
F0603HI4500V032T	4.5	32	0.014	2.63
F0603HI5000V032T	5.0	32	0.013	3.25

1. Measured at  $\leq 10\%$  of rated current and 25°C ambient  
2. Melting  $I^2t$  at 1000% of current rating

## Shape and Dimensions:



## Recommended Land Pattern:

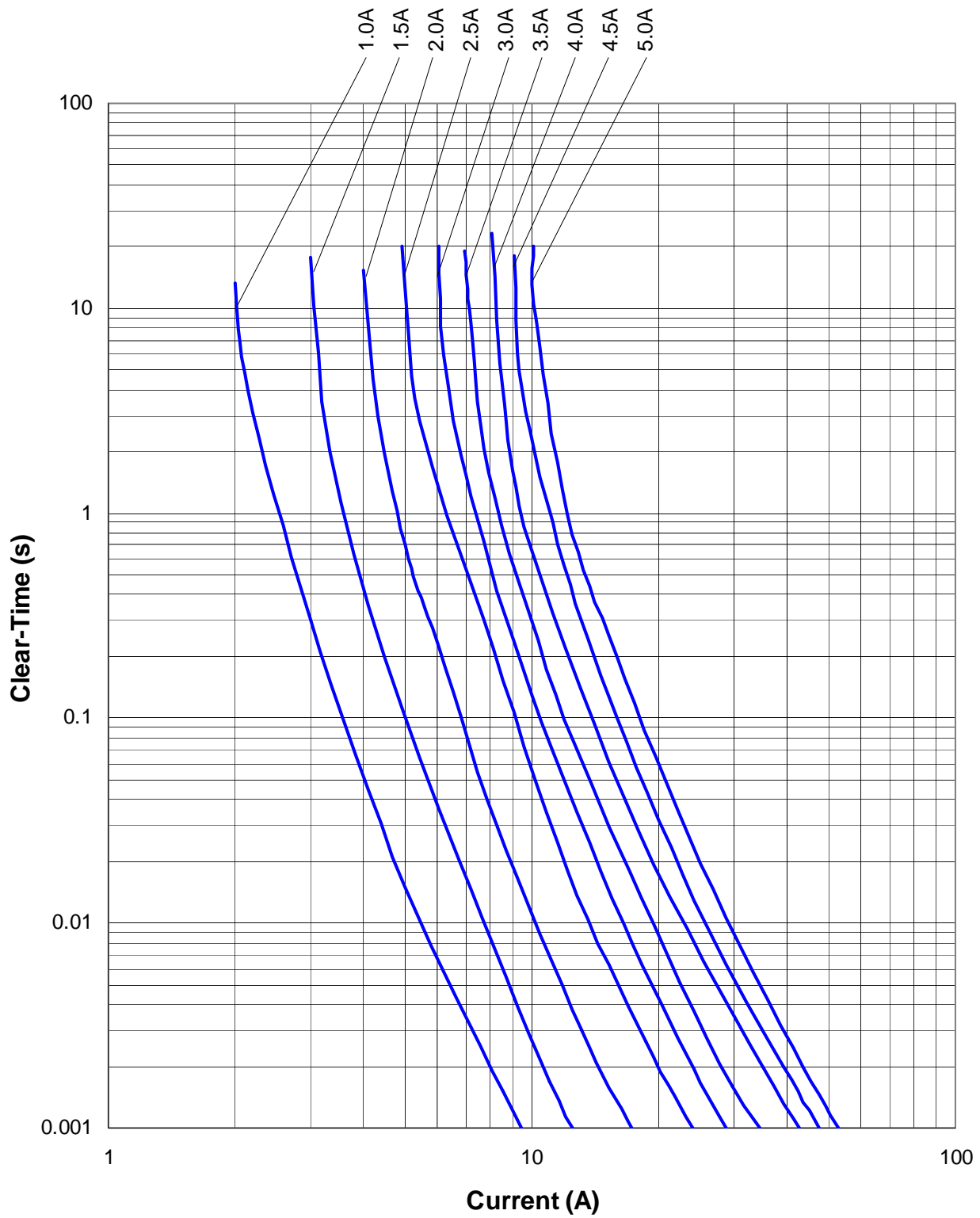


Inch(mm)

# SolidMatrix<sup>®</sup> 0603 High Inrush Current Surface Mount Fuses



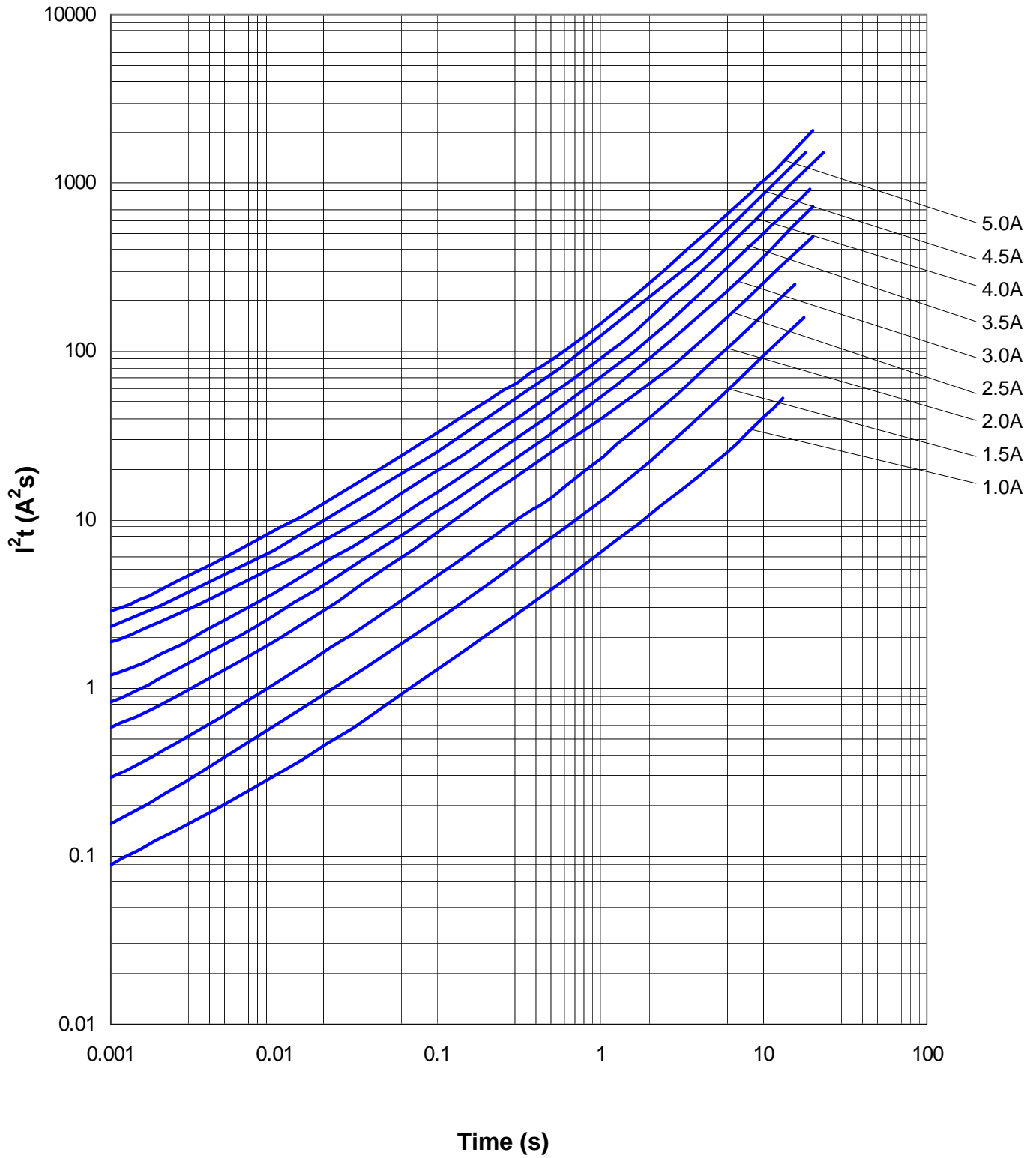
*Average Clear-Time Curves*



# SolidMatrix® 0603 High Inrush Current Surface Mount Fuses



*Average  $I^2t$  vs.  $t$  Curves*



# SolidMatrix® Surface Mount Fuses

## Product Identification:

**F 0603 FA 1000 V024 T M**

(1) (2) (3) (4) (5) (6) (7)

- (1) **Series code:** F—Chip Fuse
- (2) **Size code:** Standard EIA Chip Sizes
- (3) **Action code:** FA —Fast Acting; SB —Slow Blow; HI —High Inrush; FF—Very Fast Acting; HA—High Current
- (4) **Current rating code:** 1000 — 1000 mA ( For HA, 10—10A)
- (5) **Voltage rating code:** V024 — 24 VDC
- (6) **Package code:** T — Tape & Reel, B — Bulk
- (7) **Marking code:** M—With marking (Optional)

## Environmental Tests:

No.	Test	Requirement	Test condition	Test reference
1	Soldering heat resistance	DCR change $\leq \pm 10\%$ No mechanical damage	One dip at 260°C for 60 sec.	MIL-STD-202 Method 210
2	Solderability	Minimum 95% coverage	One dip at 255°C for 5 sec.	MIL-STD-202 Method 208
3	Thermal shock	DCR change $\leq \pm 10\%$ No mechanical damage	100 cycles between -65°C and +125°C	MIL-STD-202 Method 107
4	Moisture resistance	DCR change $\leq \pm 15\%$ No excessive corrosion	10 cycles	MIL-STD-202 Method 106
5	Salt spray	DCR change $\leq \pm 10\%$ No excessive corrosion	48 hour exposure	MIL-STD-202 Method 101
6	Mechanical vibration	DCR change $\leq \pm 10\%$ No mechanical damage	0.4" D.A. or 30 G between 5 – 3000 Hz	MIL-STD-202 Method 204
7	Mechanical shock	DCR change $\leq \pm 10\%$ No mechanical damage	1500 G, 0.5 ms, half-sine shocks	MIL-STD-202 Method 213
8	Terminal strength	No mechanical damage	30 sec. hanging for 1206 (1.5kg) and 0603 (0.5kg), 2 lb pushing for 0402	Refer to AEM QIQ007
9	Life	No electrical "opens" during testing voltage drop change shall be less than $\pm 20\%$ of initial value	80% rated current (75% for <1A fuses) for 2000 hours at ambient temperature between +20°C and +30°C	Refer to AEM QIQ106

## Electrical Specifications:

**Clear-Time Characteristics:** Same as specified on the Short Form Data Sheet

**Insulation Resistance after Opening:** 20,000 ohms typical when cleared with rated voltage applied. Fuse clearing under low voltage conditions may result in lower after clearing insulation resistance values. (Note: Under normal fault conditions (low or rated voltage conditions), AEM SolidMatrix fuses provide sufficient after clearing insulation resistance values for circuit protection.)

**Current Carrying Capacity:** 100% rated current at +25°C ambient for 4 hours minimum when evaluated per MIL-PRF-23419

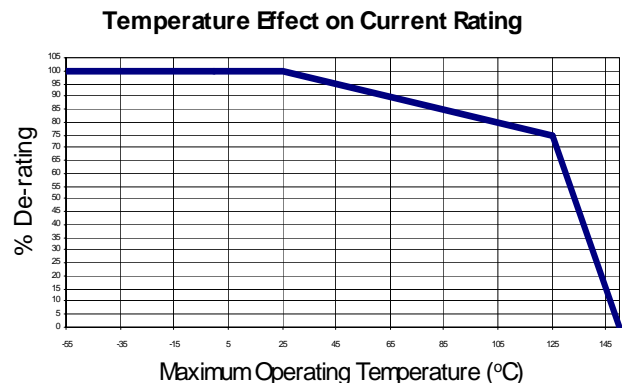
**Interrupt Ratings:** as specified in this catalog.

## Fuse Selection and Temperature De-rating Guideline:

The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25°C, the fuse shall be "de-rated".

To select a fuse from the catalog, the following rule may be followed:  
 Catalog Fuse Current Rating = Nominal Operating Current / 0.75 / % De-rating at the maximum operating temperature.

Example: At maximum operating temperature of 65°C, % De-rating is 90%. The nominal operating current is 4A. The current rating for fuse selected from the catalog shall be:  
 $4 / 0.75 / 90\% = 5.9$  or 6A.



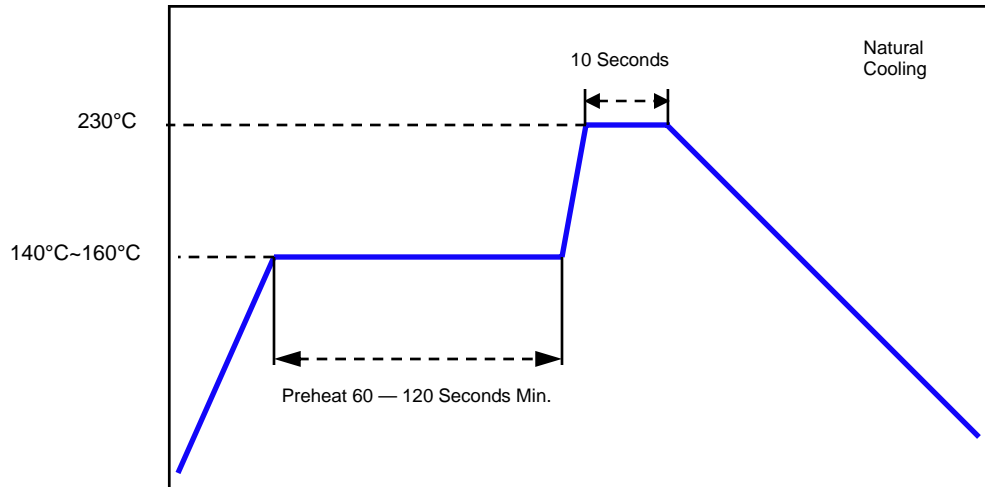
Specifications and descriptions in this literature are as accurate as known at the time of publish, but are subject to change without notice.

# SolidMatrix® Surface Mount Fuses

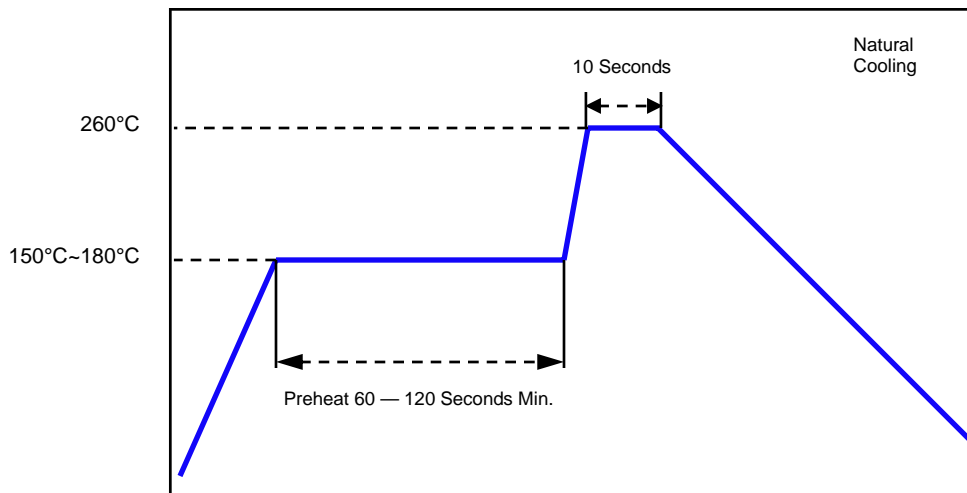


## Soldering Temperature Profiles

**Recommended Temperature Profile  
for Sn/Pb Solder**



**Recommended Temperature Profile  
for Lead-free Solder**



Recommended conditions for hand soldering:

1. Appropriate temperature (max.) of soldering iron tip/soldering time (max.): 280°C /10s or 350°C / 3s
2. Using hot air rework station with tip that can melt the solder on both terminations at the same time is strongly recommended. Do not directly contact the chip termination with the tip of soldering iron.

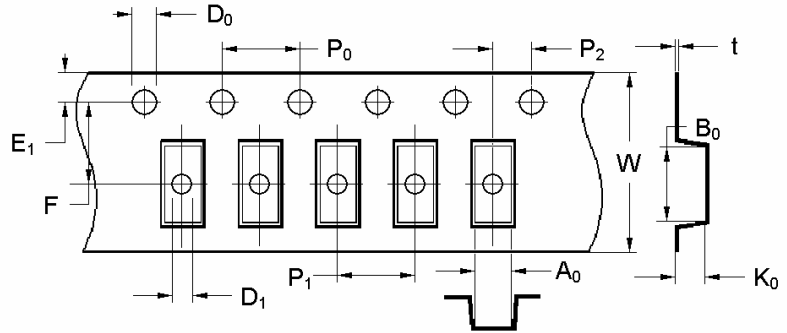
# Packaging and Storage

## Packaging

AEM's multilayer components are provided on tape-and-reel for use in pick-and-place machines or in bulk for special applications. Both tape-and-reel and bulk products are sealed in plastic bags with desiccant. The reel size can be 7 inches or 13 inches, depending on customers' preference.

### Dimensions of Tape in Inches (mm)

Size	A <sub>o</sub>	B <sub>o</sub>	K <sub>o</sub>	Type
<b>0402 (1005)</b>	0.026 ± 0.004 (0.67 ± 0.10)	0.046 ± 0.004 (1.17 ± 0.10)	0.025 ± 0.004 (0.63 ± 0.10)	Paper
<b>0603 (1608)</b>	0.039 ± 0.004 (0.98 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.037 ± 0.003 (0.95 ± 0.08)	Paper
	0.039 ± 0.004 (1.00 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.024 ± 0.003 (0.60 ± 0.08)	Paper (for FF)
	0.036 ± 0.004 (0.92 ± 0.10)	0.071 ± 0.004 (1.80 ± 0.10)	0.033 ± 0.004 (0.85 ± 0.10)	Plastic
<b>0805</b>	0.063 ± 0.004	0.093 ± 0.004	0.047 ± 0.004	Plastic
<b>1206</b>	0.071 ± 0.004	0.138 ± 0.004	0.050 ± .004	Plastic
<b>1210</b>	0.106 ± 0.004	0.137 ± 0.004	0.056 ± 0.004	Plastic
<b>1812</b>	0.144 ± 0.004	0.195 ± 0.004	0.072 ± 0.004	Plastic
<b>2220</b>	0.201 ± 0.004	0.235 ± 0.004	0.110 ± 0.004	Plastic



Size	E <sub>1</sub>	F	W	P <sub>1</sub>	P <sub>o</sub>	P <sub>2</sub>	D <sub>o</sub>	D <sub>1</sub>	t	
0402(1005)	0.069 ± 0.004 (1.75 ± 0.10)	0.138 ± 0.002 (3.50 ± 0.05)	0.318 ± 0.004 (8.00 ± 0.10)	0.079 ± 0.004 (2.00 ± 0.10)	0.157 ± 0.004 (4.00 ± 0.10)	0.040 ± 0.002 (1.00 ± 0.05)	0.059 ± 0.004/-0.00 (1.50 ± 0.10/-0.00)	N/A	0.009 ± 0.001 (0.23 ± 0.02)	
0603(1608)				0.157 ± 0.004 (4.00 ± 0.10)				0.079 ± 0.002 (2.00 ± 0.05)		0.039 max. (1.00 max.)
0805(2012)				0.318 ± 0.004 (8.00 ± 0.10)						
1206(3216)			0.472 ± 0.004 (12.00 ± 0.10)	0.004(8.00 ± 0.10)						
1210(3225)			0.004(8.00 ± 0.10)							
1812(4532)			0.004(8.00 ± 0.10)							
2220(5750)	0.004(8.00 ± 0.10)									

### Packaging Data

Chip Size	Parts on 7 inch (178 mm) Reel
<b>0402(1005)</b>	<b>10,000</b>
<b>0603(1608)</b>	<b>4,000</b>
<b>0805(2012)</b>	<b>3,000</b>
<b>1206(3216)</b>	<b>3,000</b>
<b>1210(3225)</b>	<b>2,000</b>
<b>1812(4532)</b>	<b>1,000</b>
<b>2220(5750)</b>	<b>1,000</b>

# Packaging and Storage

## ***Storage***

The maximum ambient temperature shall not exceed 40°C. Storage temperatures higher than 40°C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 70%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and should only be opened prior to use. The products should not be stored in areas where harmful gases containing sulfur or chlorine are present.

Specifications and descriptions in this literature are as accurate as known at the time of publish, but are subject to change without notice. For the most updated information, please consult the factory.

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